

CHO-BOND® 1038 and 1121

One Component Electrically Conductive Silicone Sealant (1121 Voc Free Version)

CHO-BOND 1038 is a silver-plated copper filled, one-component conductive silicone. It is designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for CHO-BOND 1038 is 0.007 inches (0.18mm). In addition, CHO-BOND 1038 may be used for EMI gasket repair, bonding, and attachment in applications where moderate strength (less than 150 psi) is required. CHO-BOND 1038's moisture cure silicone polymer system allows it to cure to the touch in 24 hours and provides a robust conductive and environmental seal over a wide range of application temperatures. For applications requiring zero volatile organic compounds (VOCs) or minimal shrinkage, Parker Chomerics offers a solvent free version of CHO-BOND 1038 called CHO-BOND 1121.

For best adhesion results, CHO-BOND 1038 should be used in conjunction with CHO-BOND 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.

Product Features

- One component
- Easy to use, no weighing or mixing required.
- Silver plated copper filler
- Excellent conductivity 0.010 ohm-cm
- Moisture cure silicone
- 30 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure.
- Non corrosive cure mechanism
- No corrosive by-products generated during curing to damage substrate.
- Medium paste
- Easy to dispense, apply and spread, can be used on overhead or vertical surfaces.
- No VOCs version: CHO-BOND 1121
- Minimal shrinkage, no permits or ventilation required.



CHO-BOND® 1038 and 1121 Product Information

Typical Properties	CHO-BOND 1038	CHO-BOND 1121	Test Method	
Polymer	Silicone	Silicone	N/A	
Filler	Silver-Plated Copper	Silver-Plated Copper	N/A	
Mix Ratio, A : B (by weight)	1-part	1-part	N/A	
Color	Gray	Gray	N/A	(Q)
Consistency	Medium Paste	Medium Paste	N/A	(Q)
Maximum DC Volume Resistivity	0.010 ohm-cm	0.010 ohm-cm	CHO-95-40-5555*	(Q/C)
Minimum Lap Shear Strength**	150 psi (1034 kPa)	150 psi (1034 kPa)	CHO-95-40-5300*	(Q/C)
Minimum Peel Strength**	4.0 lb./inch (700 N/m)	4.0 lb./inch (700 N/m)	CHO-95-40-5302*	(Q/C)
Specific Gravity	3.6	3.6	ASTM D792	(Q/C)
Hardness	80 Shore A	80 Shore A	ASTM-D2240	(Q/C)
Continuous Use Temperature	- 55°C to 125°C (-67 °F to 257 °F)	- 55°C to 125°C (-67 °F to 257 °F)	N/A	(Q)
Elevated Temperature Cure Cycle	None	None	N/A	
Room Temperature Cure	1 week***	1 week***	N/A	(Q)
Working Life	0.5 hour	0.5 hour	N/A	(Q)
Shelf Life, unopened	6 months	12 months	N/A	(Q)
Storage Conditions	70°F/21°C +/- 9°F/5°C	70°F/21°C +/- 9°F/5°C		
Minimum thickness recommended	0.007 in (0.18 mm)	0.007 in (0.18 mm)	N/A	
Maximum thickness recommended	0.125 in (3.18 mm)	0.125 in (3.18 mm)	N/A	
Volatile Organic Content (VOC)	111 g/l	0 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	775 in² (5000 cm²)	775 in² (5000 cm²)	N/A	
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	50 feet (15.2 m)	50 feet (15.2 m)	N/A	

Notes: N/A - Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

*** Chomerics' recommend minimum time to wait before applying paint over CHO-BOND 1019. Material will continue to cure after painting.

CHO-BOND® 1038 and 1121 Ordering Information

Product	Type	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1038	Sealant	113.4	1.5 fluid ounce aluminum foil tube	50-02-1038-0000	1086
CHO-BOND 1038	Sealant	113.4	1.5 fluid ounce aluminum foil tube	50-02-1038-1000	No
CHO-BOND 1038	Sealant	454	6 fluid ounce SEMCO cartridge	50-01-1038-0000	1086
CHO-BOND 1038	Sealant	454	6 fluid ounce SEMCO cartridge	50-31-1038-0000	No
CHO-BOND 1121	Sealant	454	6 fluid ounce SEMCO cartridge	50-01-1121-0000	1086
CHO-BOND 1086	Primer	10	3 dram glass vial	50-10-1086-0000	NA
CHO-BOND 1086	Primer	95	4 fluid ounce glass bottle	50-04-1086-0000	NA
CHO-BOND 1086	Primer	375	1 pint can	50-01-1086-0000	NA

Note: Supplied in a plastic 6 fluid ounce cartridge suitable for standard air-operated caulking guns. To achieve maximum shelf life/pot life, caulking gun should be activated with dry bottled nitrogen. Please refer to Parker Chomerics Surface Preparation and CHO-BOND Polythioether Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.



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CHODS1234 September 2026

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